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ITO-220



Pin Definition:

1. Gate
2. Drain
3. Source

PRODUCT SUMMARY

| V _{DS} (V) | R _{DS(on)} (Ω)(max) | I _D (A) |
|---------------------|------------------------------|--------------------|
| 700 | 0.9 @ V _{GS} =10V | 8 |

General Description

The TSM8N70 N-Channel enhancement mode Power MOSFET is produced by planar stripe DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode.

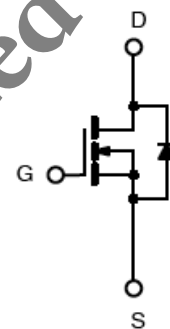
Features

- Low R_{DS(ON)} 0.75Ω (Typ.)
- Low gate charge typical @ 32nC (Typ.)
- Low Crss typical @ 13.7pF (Typ.)
- Fast Switching

Ordering Information

| Part No. | Package | Packing |
|---------------|---------|--------------|
| TSM8N70CI C0 | ITO-220 | 50pcs / Tube |
| TSM8N70CI C0G | ITO-220 | 50pcs / Tube |

Block Diagram



N-Channel MOSFET

Absolute Maximum Rating (T_a = 25°C unless otherwise noted)

| Parameter | Symbol | Limit | Unit |
|-------------------------------------------------|------------------|------------------------|------|
| Drain-Source Voltage | V _{DS} | 700 | V |
| Gate-Source Voltage | V _{GS} | ±30 | V |
| Continuous Drain Current | I _D | T _C = 25°C | 8 |
| | | T _C = 100°C | 4.8 |
| Pulsed Drain Current * | I _{DM} | 32 | A |
| Single Pulse Avalanche Energy (Note 2) | E _{AS} | 266 | mJ |
| Avalanche Current (Repetitive) (Note 2) | I _{AS} | 8 | A |
| Single Pulse Avalanche Energy (Note 1) | E _{AR} | 11.6 | mJ |
| Avalanche Current (Repetitive) (Note 1) | I _{AR} | 8 | A |
| Total Power Dissipation @ T _C = 25°C | P _{TOT} | 40 | W |
| Operating Junction Temperature | T _J | 150 | °C |
| Storage Temperature Range | T _{STG} | -55 to +150 | °C |

Note: Limited by maximum junction temperature

Thermal Performance

| Parameter | Symbol | Limit | Unit |
|------------------------------------------|------------------|-------|------|
| Thermal Resistance - Junction to Case | R _{θJC} | 3.1 | °C/W |
| Thermal Resistance - Junction to Ambient | R _{θJA} | 62.5 | °C/W |

Notes: Surface mounted on FR4 board t ≤ 10sec

Electrical Specifications (Ta = 25°C unless otherwise noted)

| Parameter | Conditions | Symbol | Min | Typ | Max | Unit |
|-------------------------------------------------------|---------------------------------------------------------------|--------------|-----|------|----------|----------|
| Static | | | | | | |
| Drain-Source Breakdown Voltage | $V_{GS} = 0V, I_D = 250\mu A$ | BV_{DSS} | 700 | -- | -- | V |
| Drain-Source On-State Resistance | $V_{GS} = 10V, I_D = 4A$ | $R_{DS(ON)}$ | -- | 0.75 | 0.9 | Ω |
| Gate Threshold Voltage | $V_{DS} = V_{GS}, I_D = 250\mu A$ | $V_{GS(TH)}$ | 2.0 | -- | 4.0 | V |
| Zero Gate Voltage Drain Current | $V_{DS} = 700V, V_{GS} = 0V$ | I_{DSS} | -- | -- | 1 | μA |
| Gate Body Leakage | $V_{GS} = \pm 30V, V_{DS} = 0V$ | I_{GSS} | -- | -- | ± 10 | μA |
| Forward Transfer Conductance | $V_{DS} = 10V, I_D = 4A$ | g_{fs} | -- | 11 | -- | S |
| Dynamic | | | | | | |
| Total Gate Charge | $V_{DS} = 560V, I_D = 8A,$ $V_{GS} = 10V$ | Q_g | -- | 32 | -- | nC |
| Gate-Source Charge | | Q_{gs} | -- | 9 | -- | |
| Gate-Drain Charge | | Q_{gd} | -- | 8 | -- | |
| Input Capacitance | $V_{DS} = 25V, V_{GS} = 0V,$ $f = 1.0MHz$ | C_{iss} | -- | 2006 | -- | pF |
| Output Capacitance | | C_{oss} | -- | 148 | -- | |
| Reverse Transfer Capacitance | | C_{rss} | -- | 13.7 | -- | |
| Switching | | | | | | |
| Turn-On Delay Time | $V_{GS} = 10V, I_D = 10A,$ $V_{DD} = 300V, R_G = 25\Omega$ | $t_{d(on)}$ | -- | 23 | -- | nS |
| Turn-On Rise Time | | t_r | -- | 69 | -- | |
| Turn-Off Delay Time | | $t_{d(off)}$ | -- | 144 | -- | |
| Turn-Off Fall Time | | t_f | -- | 77 | -- | |
| Source-Drain Diode Ratings and Characteristics | | | | | | |
| Source Current | Integral reverse diode in the MOSFET | I_S | -- | -- | 8 | A |
| Source Current (Pulse) | | I_{SM} | -- | -- | 32 | A |
| Diode Forward Voltage | $I_S = 8A, V_{GS} = 0V$ | V_{SD} | -- | -- | 1.4 | V |
| Reverse Recovery Time | $V_{GS} = 0V, I_S = 8A,$ | t_{fr} | -- | 420 | -- | nS |
| Reverse Recovery Charge | $di_F/dt = 100A/\mu s$ | Q_{fr} | -- | 4.2 | -- | μC |

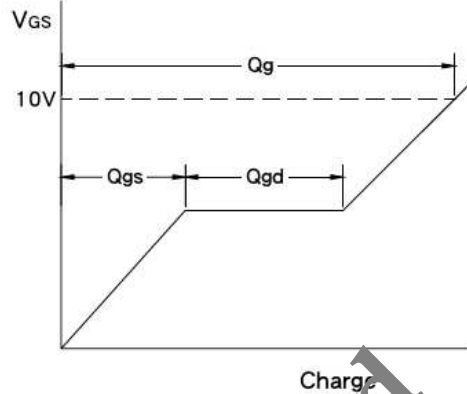
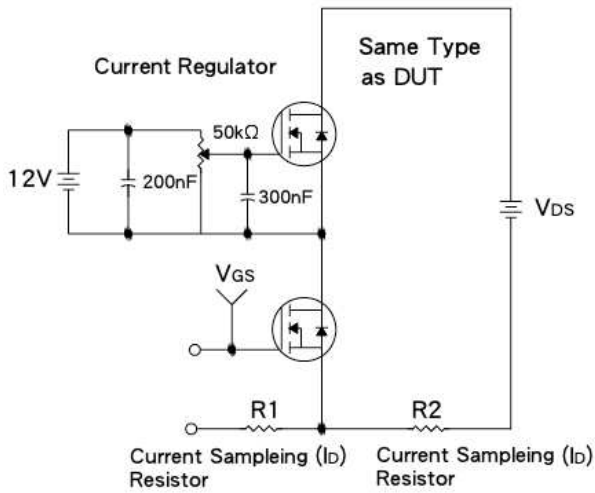
Note 1: Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

Note 2: $V_{DD} = 50V, I_{AS} = 8A, L = 7.74mH, R_G = 25\Omega, \text{Starting } T_J = 25^\circ C$

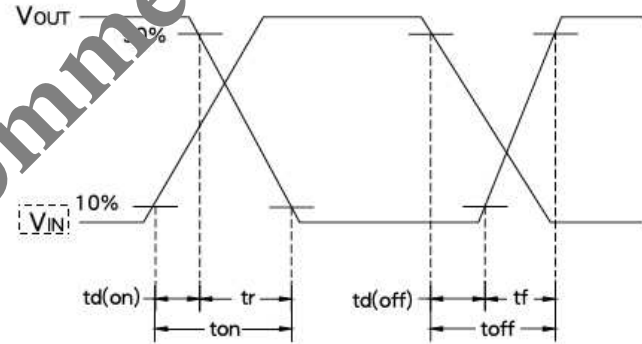
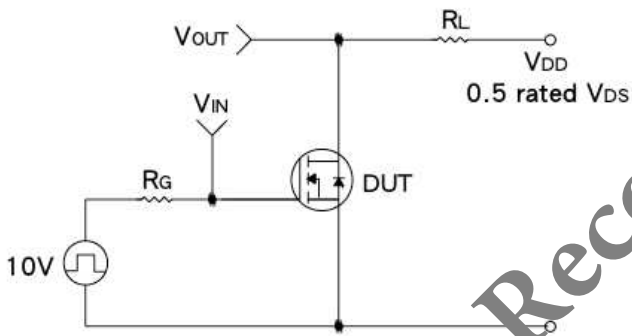
Note 3: Pulse test: pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$

Note 4: Essentially Independent of Operating Temperature

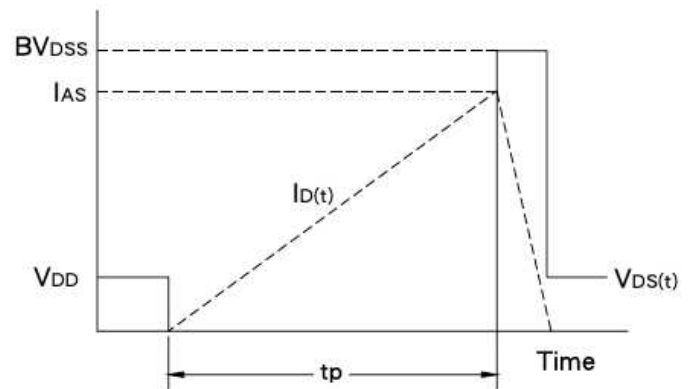
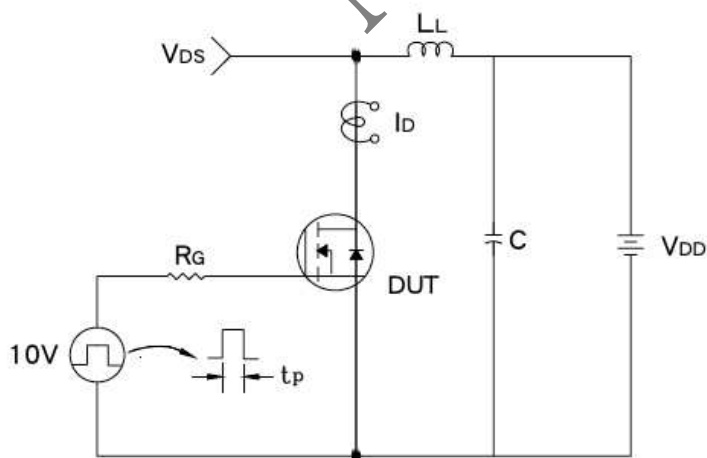
Gate Charge Test Circuit & Waveform



Resistive Switching Test Circuit & Waveform

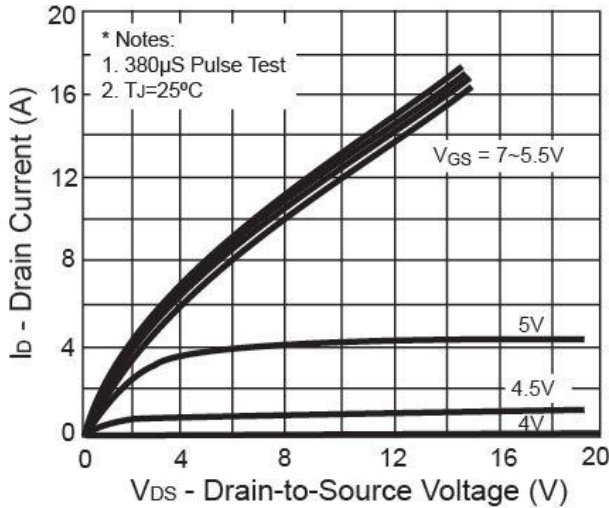


EAS Test Circuit & Waveform

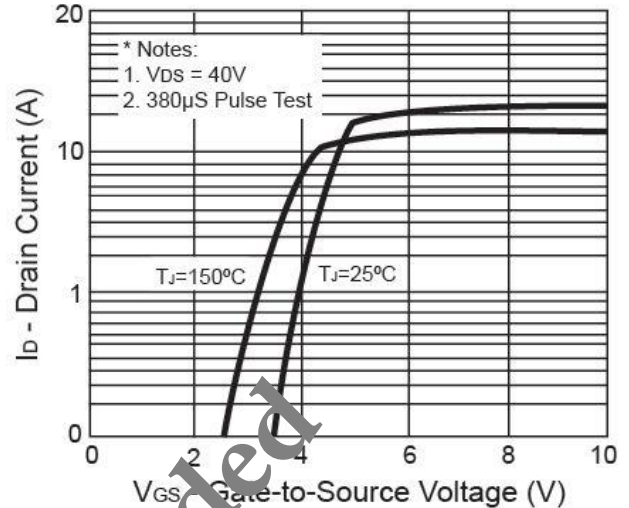


Electrical Characteristics Curve (Ta = 25°C, unless otherwise noted)

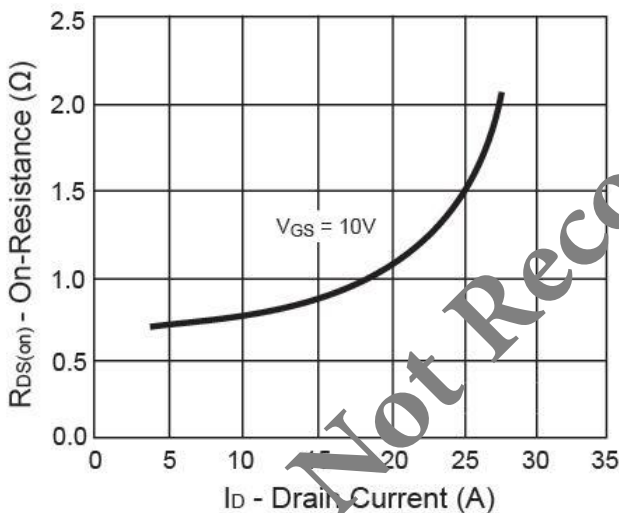
Output Characteristics



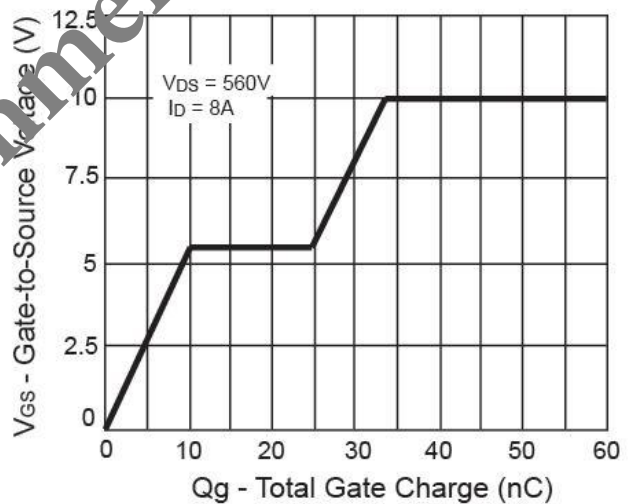
Transfer Characteristics



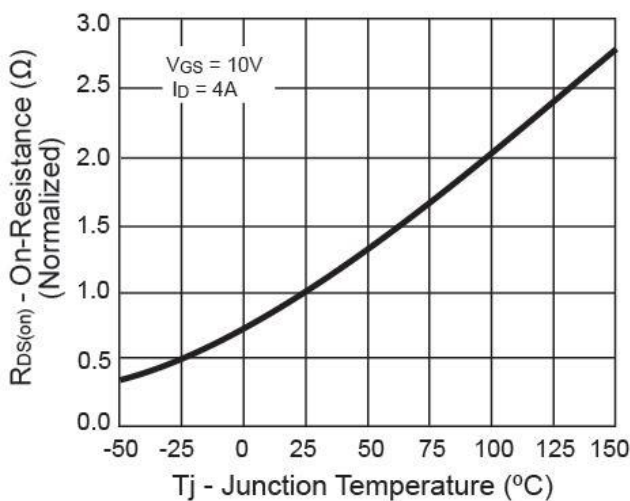
On-Resistance vs. Drain Current



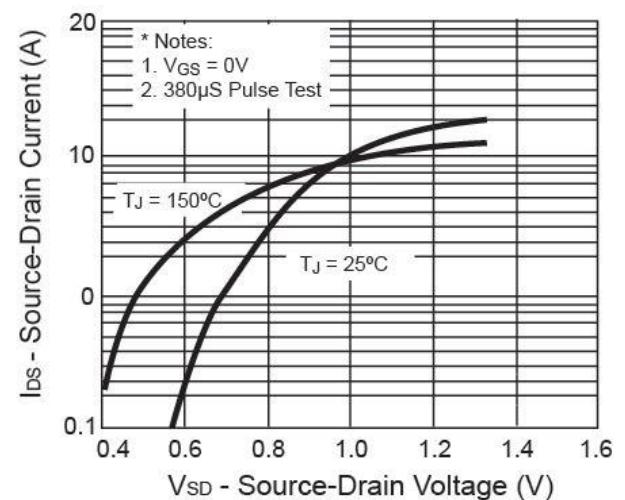
Gate Charge



On-Resistance vs. Junction Temperature

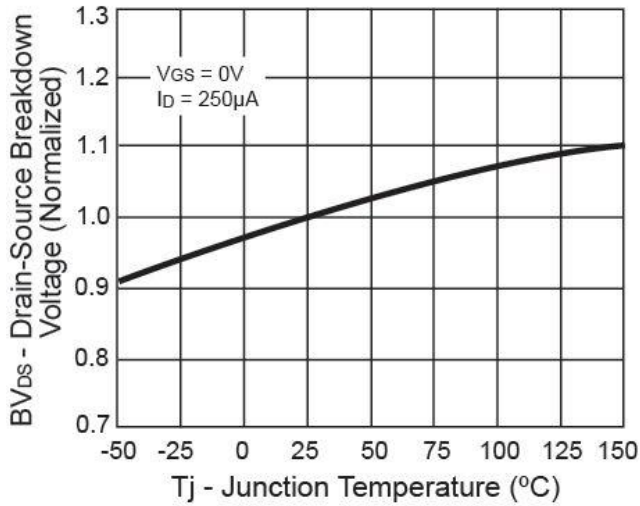


Source-Drain Diode Forward Voltage

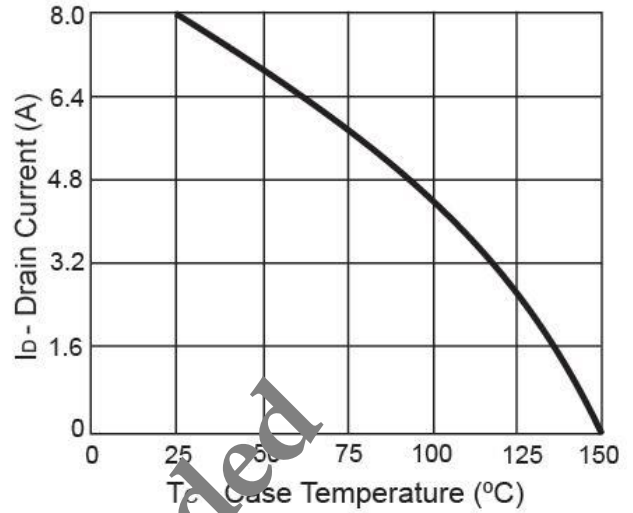


Electrical Characteristics Curve ($T_a = 25^\circ\text{C}$, unless otherwise noted)

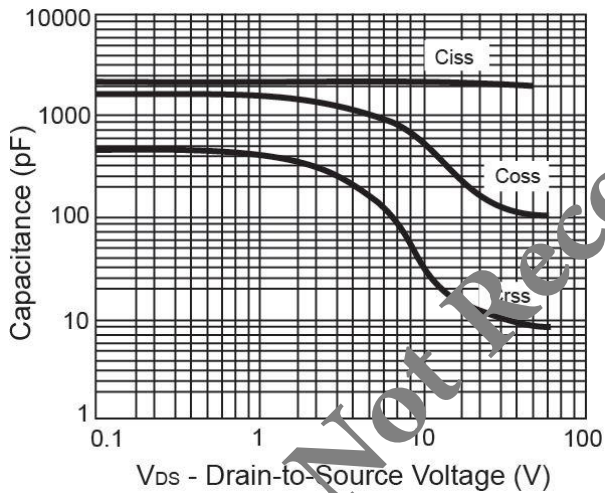
BV_{DS} vs. Junction Temperature



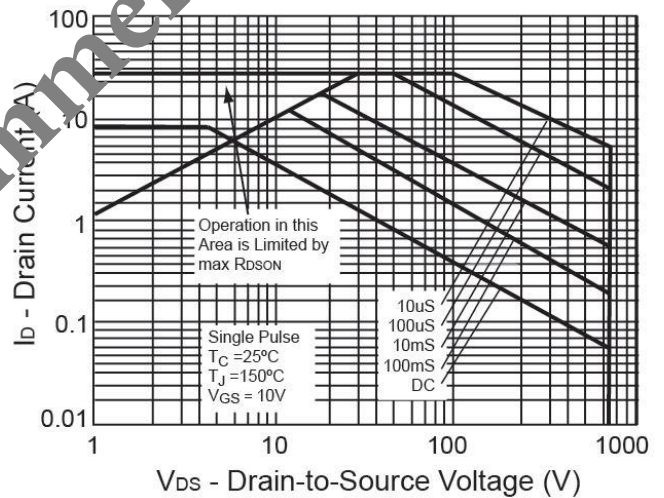
Drain Current vs., Case Temperature



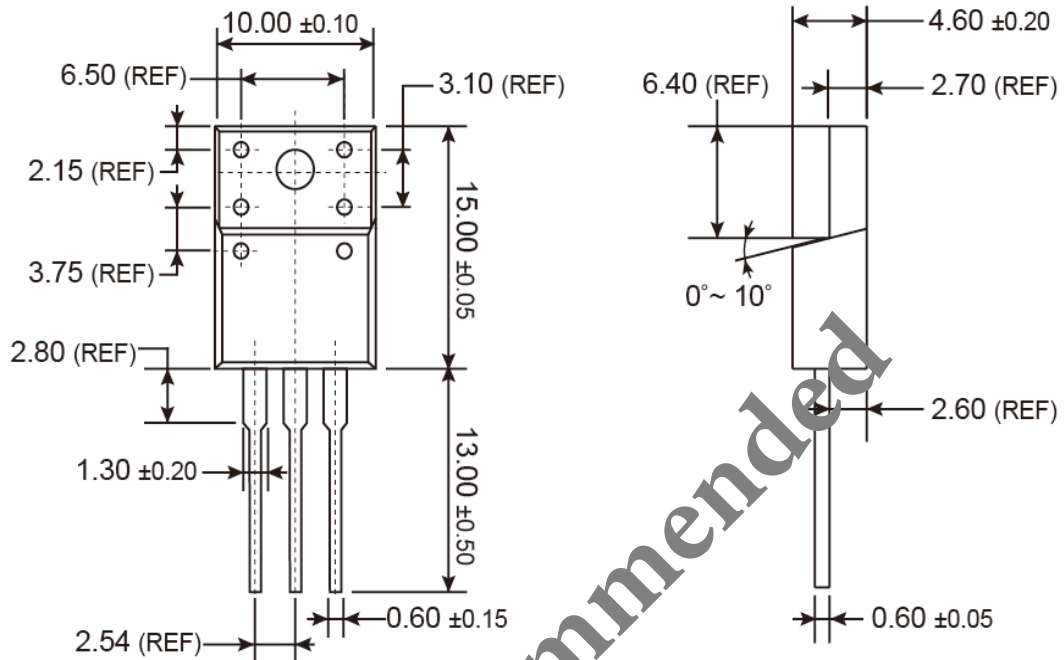
Capacitance



Maximum Safe Operating Area

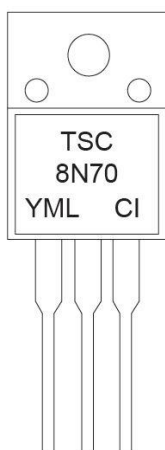


ITO-220 Mechanical Drawing



Unit: Millimeters

Marking Diagram



Y = Year Code
M = Month Code
(A=Jan, B=Feb, C=Mar, D=Apl, E=May, F=Jun, G=Jul, H=Aug, I=Sep, J=Oct, K=Nov, L=Dec)
L = Lot Code

Not Recommended

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